

Title (en)  
PALLADIUM AND PALLADIUM ALLOYS ELECTROPLATING PROCEDURE

Publication  
**EP 0073236 B1 19851009 (EN)**

Application  
**EP 82901061 A 19820218**

Priority  
US 23915181 A 19810227

Abstract (en)  
[origin: EP0059452A2] A procedure for electroplating palladium and palladium alloys is disclosed which permits rapid and efficient plating and yields ductile, adherent palladium films. The electroplating bath comprises a unique complex of palladium and aliphatic polyamine the latter having from 3 to 20 carbon atoms and may have at least one substituent selected from hydrogen, hydroxide, chloride and bromide. The bath is highly stable and does not adversely affect the base material being plated.

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IPC 8 full level  
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**C25D 3/52** (2013.01)

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DE 2939920 A1 19810409 - HERAEUS GMBH W C [DE]

Cited by  
DE4444232C1; US5549810A; DE4431847A1; DE4431847C2; DE4431847C5; EP0701281A2

Designated contracting state (EPC)  
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**EP 0059452 A2 19820908**; **EP 0059452 A3 19821110**; **EP 0059452 B1 19851009**; CA 1189016 A 19850618; DE 3266736 D1 19851114; EP 0073236 A1 19830309; EP 0073236 A4 19830114; EP 0073236 B1 19851009; GB 2112018 A 19830713; GB 2112018 B 19840815; HK 48088 A 19880708; JP H0219197 B2 19900427; JP S58500289 A 19830224; WO 8202908 A1 19820902

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